



Product Change Notification: BLAS-15VJAK507

Date:

26-Jun-2026

Product Category:

Linear Regulators

Notification Subject:

CCB 7594 Final Notice: Qualification of ATP7 as an additional assembly site for selected MIC94355, MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN (1.6x1.6x0.6mm) package.

Affected CPNs:

[BLAS-15VJAK507_Affected_CPN_06262026.pdf](#)

[BLAS-15VJAK507_Affected_CPN_06262026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for selected MIC94355, MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN (1.6x1.6x0.6mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Unisem Chengdu Co.,Ltd. (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Amkor Technology Philippines (P3/P4),	Yes

			INC. (ATP7)	
Wire Material	Au	Au	CuPdAu	Yes
Die Attach Material	8290	8290	CDF215	Yes
Molding Compound Material	G770HP	G770HP	G631BQF	Yes
Lead-Frame Material	C194	C194	C7025	Yes
Lead-Frame Design	See Pre and Post Change for Comparison.			

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying ATP7 as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 July 2026 (date code: 2631)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2025					>	June 2026					July 2026			
Work Week	18	19	20	21	22		23	24	25	26	27	28	29	30	31
Initial PCN Issue Date				x											
Qual Report Availability										x					
Final PCN Issue Date										x					
Estimated Implementation Date															x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

May 19, 2025: Issued initial notification.

September 11, 2025: Re-issued initial notification to update the die attach material from ATB-F125E to CDF215.

June 26, 2026: Issued final notification. Added the "Change (Yes/No)" column to the Pre- and Post-Change Summary table. Updated the Pre- and Post- Change attachment. Attached the qualification report. Provided estimated first ship date to be on July 30, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_BLAS-15VJAK507 Qual Report.pdf

PCN_BLAS-15VJAK507-Pre and Post Change Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MIC94355-MYMT-T5

MIC94345-MYMT-T5

MIC94305YMT-T5

MIC94355-GYMT-T5

MIC94355-OYMT-T5

MIC94355-OYMT-TR

MIC94355-GYMT-TR

MIC94345-SYMT-TR

MIC94345-SYMT-T5

MIC94345-GYMT-TR

MIC94345-4YMT-TR

MIC94325YMT-TR

MIC94325YMT-T5

MIC94305YMT-TR

MIC94355-SYMT-TR

MIC94345-MYMT-TR

MIC94345-GYMT-T5

MIC94345-4YMT-T5

MIC94355-SYMT-T5

MIC94355-MYMT-TR



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QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: BLAS-15VJAK507

Date:
June 17, 2026

**Qualification of ATP7 as an additional assembly site for selected MIC94355,
MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN
(1.6x1.6x0.6mm) package.**



MICROCHIP Package Qualification Report

Purpose: Qualification of ATP7 as an additional assembly site for selected MIC94355, MIC94305, MIC94325 and MIC94345 device families available in 6L UDFN (1.6x1.6x0.6mm) package.

CCB No.: 7594

Misc.	Assembly site	ATP7
	BD Number	BD-003141-02
	MP Code (MPC)	TANB1YHKAA04
	Part Number (CPN)	MIC94325YMT-TR
	Assembly Shipping Media	Cannister
	Base Quantity Multiple (BQM)	500; 5,000
	Qual ID	R2501334 Rev. A
Lead-Frame	Paddle size	55x26mils
	Material	C7025
	DAP Surface Prep	PPF
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes (Half Etch)
	Part Number	101431117
	Lead Plating	NiPdAu
	Strip Size	70x250mm
	Strip Density	3540
Bond Wire	Material	CuPdAu
Die Attach	Part Number	CDF215
	Conductive	Yes
MC	Part Number	G631BQF
PKG	PKG Type	UDFN
	Pin/Ball Count	6
	PKG width/size	1.6x1.6x0.6mm



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Package Qualification Report

Manufacturing Information:

Assembly Lot No.
ATP7262000003.100
ATP7262000004.100
ATP7262000006.100

Conclusion:

Qualification of TANB1 mask / MIC94325YMT-TR product / CuPdAu wire in 6L UDFN 1.6x1.6x0.6mm (HKA) package at ATP7 site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2501334-1 ATP7262000003.100	R2501334-2 ATP7262000004.100	R2501334-3 ATP7262000006.100
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: TMT	25°C		
RESULTS	PASSED		



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Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 3 lot;		
Lot ID	R2501334-1 ATP7262000003.100	R2501334-2 ATP7262000004.100	R2501334-3 ATP7262000006.100
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: TMT	25°C		
RESULTS	PASSED		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP, refer to FRM-39000		
Lot ID	R2501334-1 ATP7262000003.100	R2501334-2 ATP7262000004.100	R2501334-3 ATP7262000006.100
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/5	N/A	N/A
Electrical Test Tester: TMT	25°C		
RESULTS	PASSED		



MICROCHIP Package Qualification Report

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH /96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501334-1 ATP7262000003.100	R2501334-2 ATP7262000004.100	R2501334-3 ATP7262000006.100
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: TMT	25°C		
RESULTS	PASSED		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH /192 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501334-1 ATP7262000003.100	R2501334-2 ATP7262000004.100	R2501334-3 ATP7262000006.100
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: TMT	25°C		
RESULTS	PASSED		

Solderability

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 1 hours Steam age. Dip at 215°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
RESULTS	PASSED



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Package Qualification Report

Solderability

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 1 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
	PASSED

Physical Dimension

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30
	PASSED

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
	PASSED



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Package Qualification Report

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5
	PASSED

Wire sweep

Test Method	X-ray
Test Criteria	15%
Required Sample Size	15 wires each lot / 3 lots
Result (Fail / Pass)	0/45
	PASSED

CCB 7594

Pre and Post Change Summary

PCN #: BLAS-15VJAK507



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Pre and Post Change Summary

UNIC	ATP7				
<table><tr><td>Lead-Frame Material</td><td>C194</td></tr></table>	Lead-Frame Material	C194	<table><tr><td>Lead-Frame Material</td><td>C7025</td></tr></table>	Lead-Frame Material	C7025
Lead-Frame Material	C194				
Lead-Frame Material	C7025				

Note: Not to scale